

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS2107A	Jul-96	9623 A6	ANAM, K.	DN604282AAB1	1.2μ NITRIDE	16 SOIC

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Preconditioning (P/C):
HTC Vapor Phase
P-17820

<u>Electrical</u>	<u>Cum %</u>
233/0	0.0%

Sonoscan
P-17863

<u>Post Vapor Phase</u>
2/0

Infant / High Voltage Life
125°C, 7.0 V.
P-17864, P-17904

<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
231/0	77/0	77/3	140 Fits
		F1,F2,F3	

*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0

Temp Cycle
-55°C to +125°C
P-17905

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
50/0	50/0	0.0%

Biased Moisture (HAST)
120°C/85% RH, 5.5 V.
P-17906

<u>100 Hr</u>	<u>Cum %</u>
66/0	0.0%

Autoclave
121°C/100% RH, 2 Atmos
P-17907

<u>96 Hr</u>	<u>Cum %</u>
38/0	0.0%

Failure Mode

Failure Analysis

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Failure Analysis

F1: Continuity
F2: Term Resistance

In process, 960300
In process, 960300

F3: Functional

In process, 960300